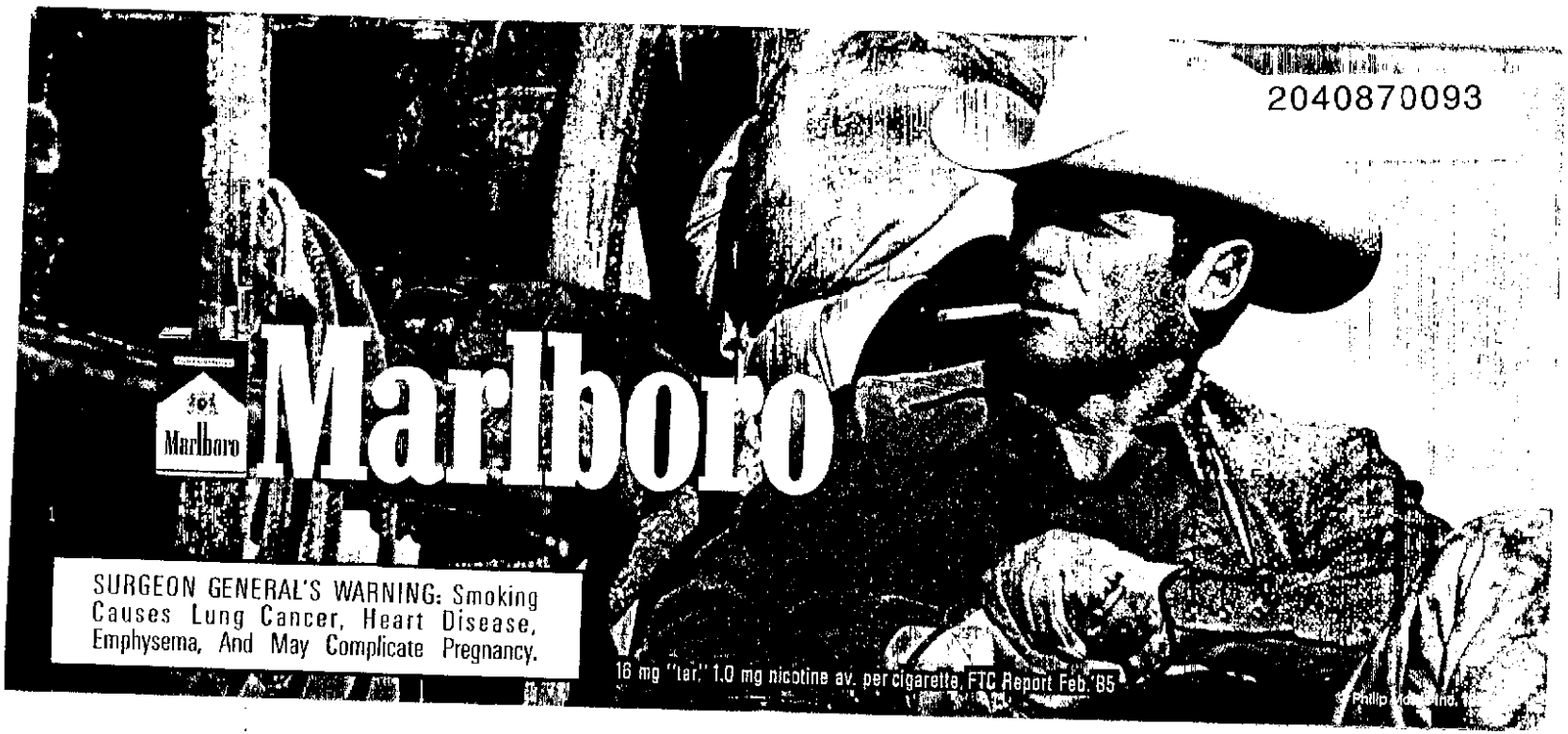

Source: https://www.industrydocuments.ucsf.edu/docs/hpwm0004